

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary



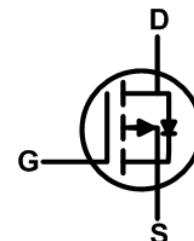
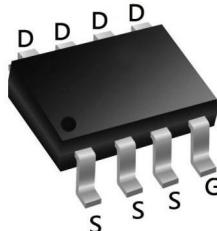
BVDSS	RDS(on)	ID
-100V	254mΩ	-5A

### Description

The XR5P10S is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XR5P10S meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

### SOP8 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	-5	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	-3.6	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-26.8	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	109	mJ
I <sub>AS</sub>	Avalanche Current	---	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	40	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	---	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	3.7	°C/W

Electrical Characteristics ( $T_J=25^\circ C$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ C, I_D=1mA$	---	---	---	$V/C$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-2A$	---	254	330	$m\Omega$
		$V_{GS}=-4.5V, I_D=-1A$	---	271	352	
		$V_{GS}=-2.5V, I_D=-1A$	---	---	---	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1	-1.7	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/C$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-100V, V_{GS}=0V, T_J=25^\circ C$	---	---	-1	$uA$
		$V_{DS}=-100V, V_{GS}=0V, T_J=100^\circ C$	---	---	-100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-4A$	---	10	---	S
$Q_g$	Total Gate Charge	$V_{DS}=-50V, V_{GS}=-10V, I_D=-3A$	---	19.6	---	$nC$
$Q_{gs}$	Gate-Source Charge		---	6	---	
$Q_{gd}$	Gate-Drain Charge		---	4.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-50V, V_{GS}=-10V, R_G=3\Omega$	---	13.5	---	$ns$
$T_r$	Rise Time		---	3.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	42	---	
$T_f$	Fall Time		---	6.4	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-50V, V_{GS}=0V, f=1MHz$	---	1199	---	$pF$
$C_{oss}$	Output Capacitance		---	33.8	---	
$C_{rss}$	Reverse Transfer Capacitance		---	28.2	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	-5	A
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	-20	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1.2	V
$t_{rr}$	Reverse Recovery Time	$ I_F =-3A, dI/dt=100A/\mu s, T_J=25^\circ C$	---	42.9	---	$nS$
$Q_{rr}$	Reverse Recovery Charge		---	83.7	---	$nC$

Note :

1 The data is tested by a surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2oz copper.

2 The data is tested by a pulsed pulse width &lt; 300us, duty cycle &lt; 2%.

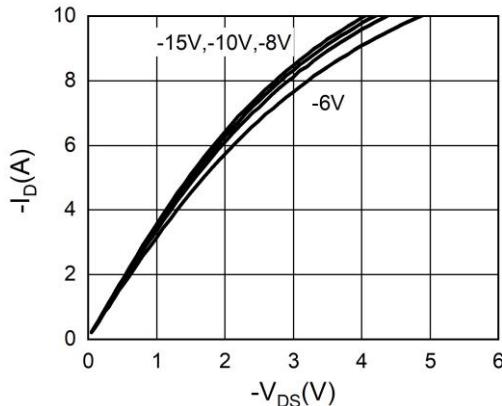
3 The EAS data shows Max. rating . The test condition is V<sub>DM</sub>=0, V<sub>DD</sub>=-50V, V<sub>G</sub>=-10V, R<sub>g</sub>=25Ω, L=0.5mH.

4 The power dissipation is limited by 50°C junction temperature

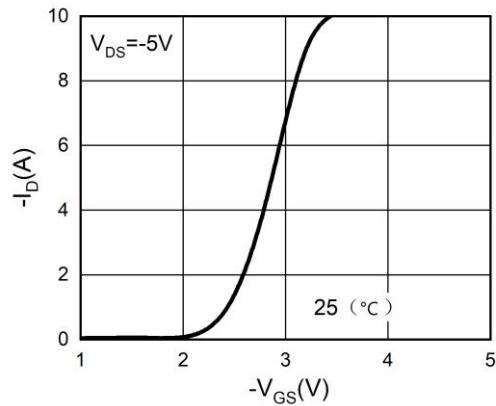
The data is theoretically the same as  $I_{DSS}$  and  $I_{DMA}$ . In real applications, it should be limited by total power dissipation.

## Typical Electrical And Thermal Characteristics (Curves)

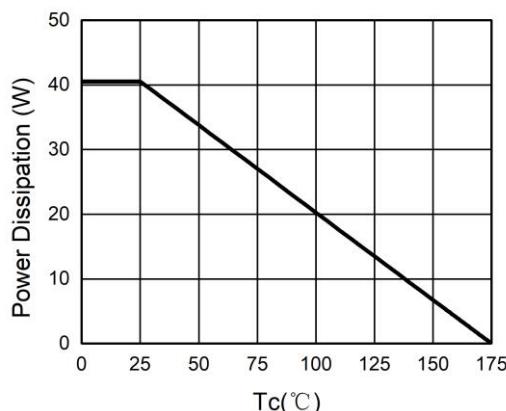
**Figure 1. Output Characteristics**



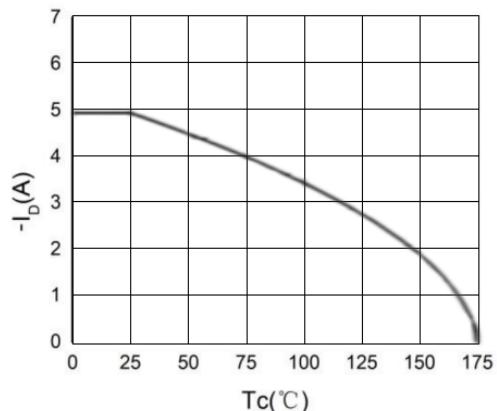
**Figure 2. Transfer Characteristics**



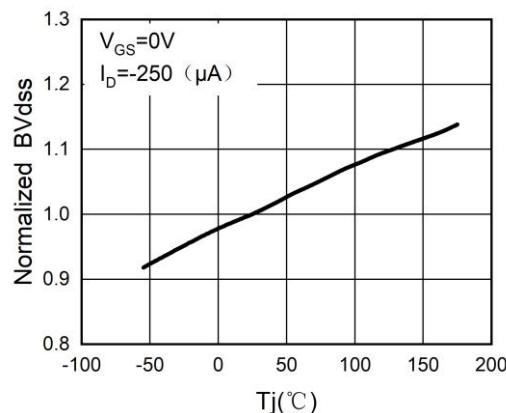
**Figure 3. Power Dissipation**



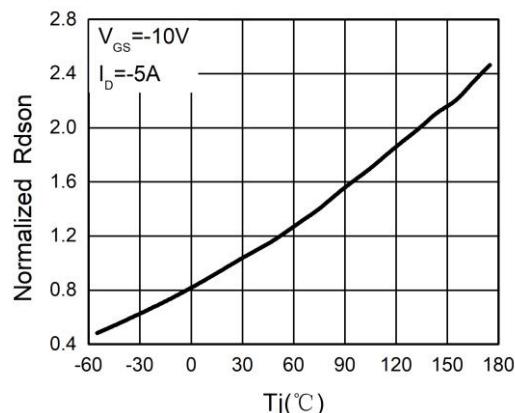
**Figure 4. Drain Current**

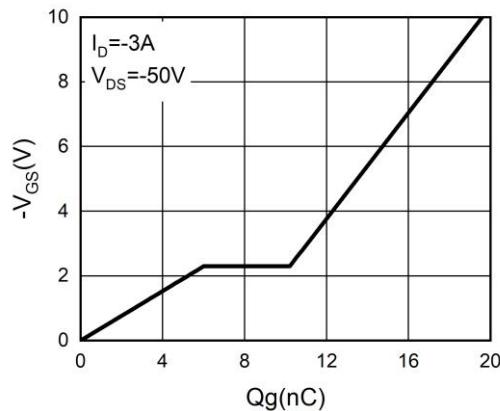
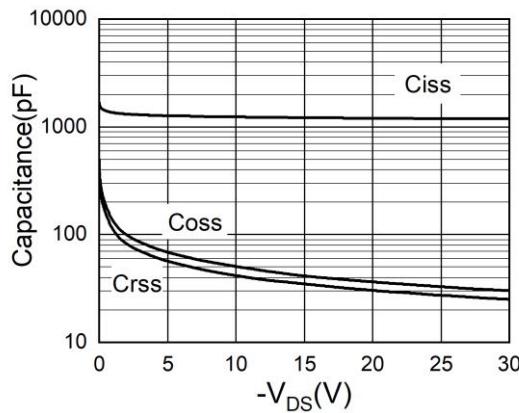
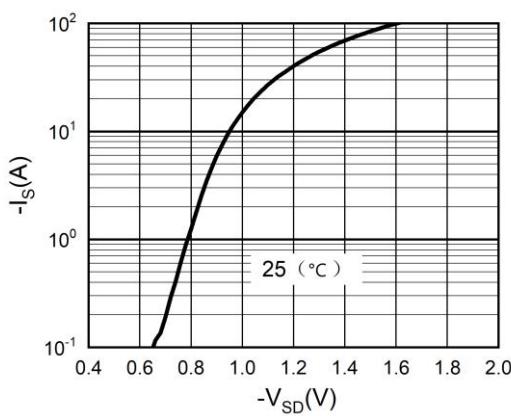
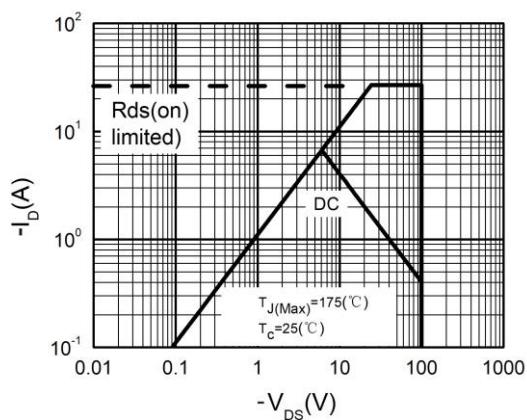


**Figure 5. BV<sub>DSS</sub> vs Junction Temperature**



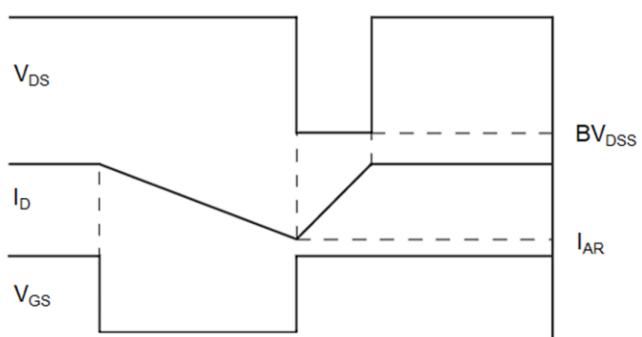
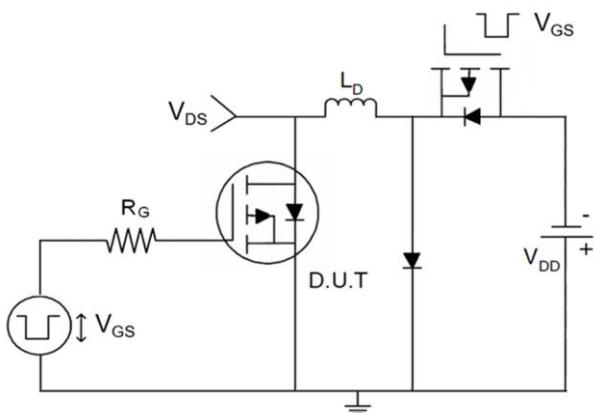
**Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature**



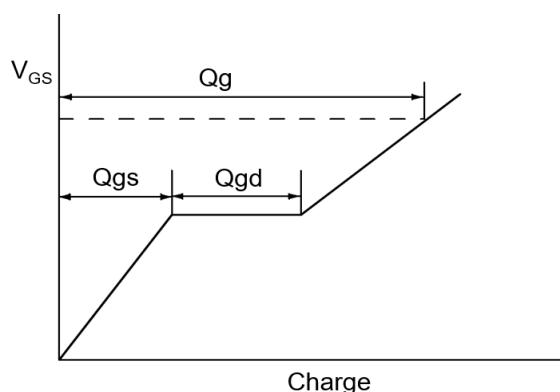
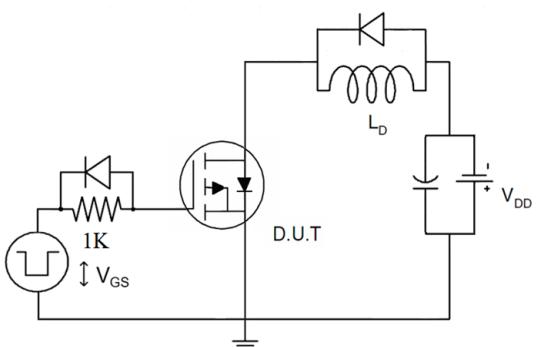
**Figure 7. Gate Charge Waveforms****Figure 8. Capacitance****Figure 9. Body-Diode Characteristics****Figure 10. Maximum Safe Operating Area**

## Test Circuit

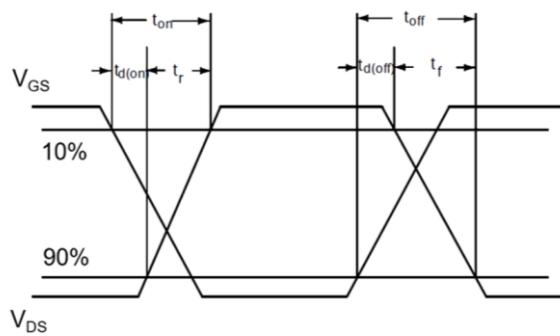
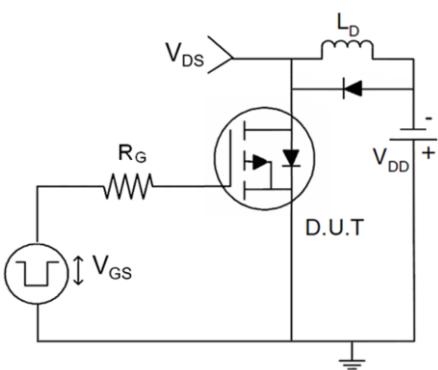
P-Ch 100V Fast Switching MOSFETs

1)  $E_{AS}$  Test Circuits

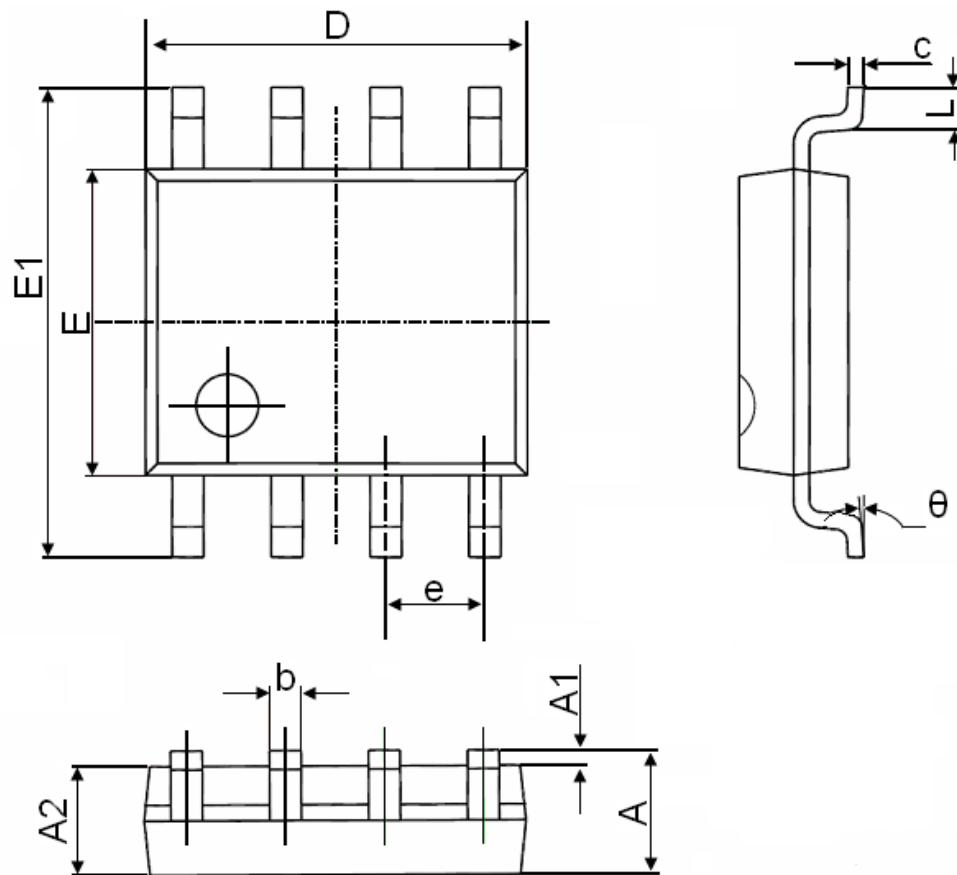
## 2) Gate Charge Test Circuit



## 3) Switch Time Test Circuit



## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°